

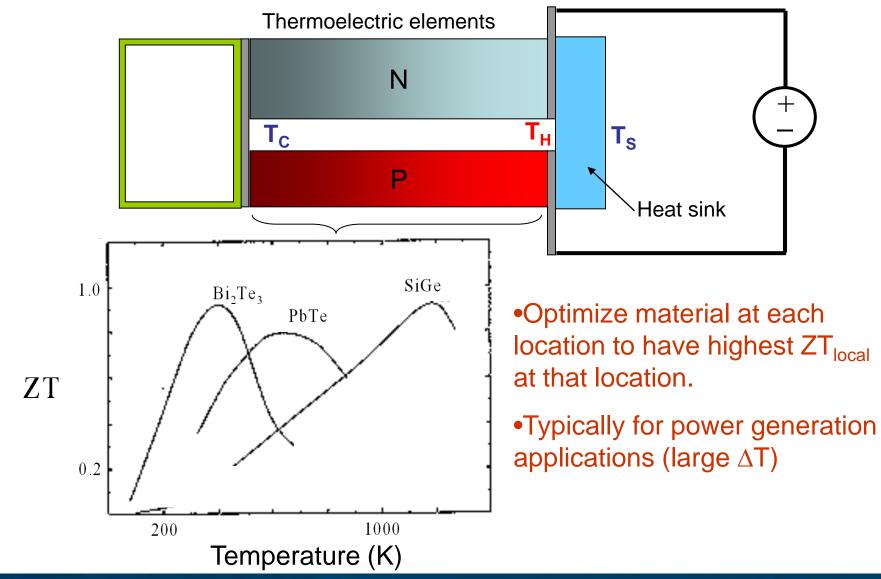
Thermoelectricity: From Atoms to Systems

Week 4: Thermoelectric Systems Lecture 4.4: Graded materials, TE leg geometry impact

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Conventional Functionally Graded or Segmented Thermoelectric Materials







Thermoelectric properties of a composite medium

David J. Bergman and Ohad Levy

We study the thermoelectric properties of a composite medium. ... We prove that $Z_{effective}$ of the composite can never exceed the largest value of Z in any component.

(rigorous proof for two-component system)

$$Q_{e11} = \frac{1}{V} \int dV (Q_{11}E_1^{(1)^2} + 2Q_{12}E_1^{(1)} \cdot E_2^{(1)} + Q_{22}E_2^{(1)^2})$$

Journal of Applied Physics -- December 1, 1991 - V.70 (11), pp. 6821-6833



Compatibility Factor



Volume 91, Number 14

2003

PHYSICAL REVIEW LETTERS

Thermoelectric Efficiency and Compatibility

G. Jeffrey Snyder and Tristan S. Ursell

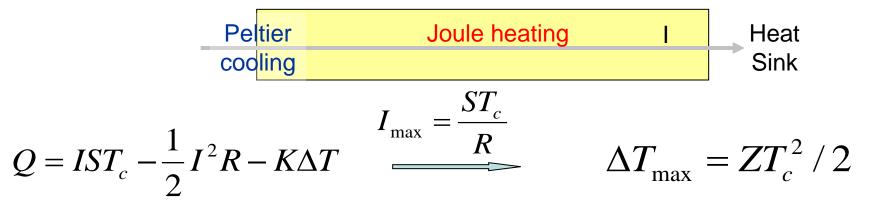
A new materials property $s=(\sqrt{1+zT-1})/(\alpha T)$, which we call the compatibility factor. Materials with dissimilar compatibility factors cannot be combined by segmentation into an efficient thermoelectric generator. Thus, control of the compatibility factor s is, in addition to z, essential for efficient operation of a thermoelectric device

Application of the compatibility factor to the design of segmented and cascaded thermoelectric generators

G. J. Snyder; Appl. Phys. Lett. 84, 2436 (2004)

... Cascaded generators avoid the compatibility problem.

Maximum cooling of uniform thermoelectrics

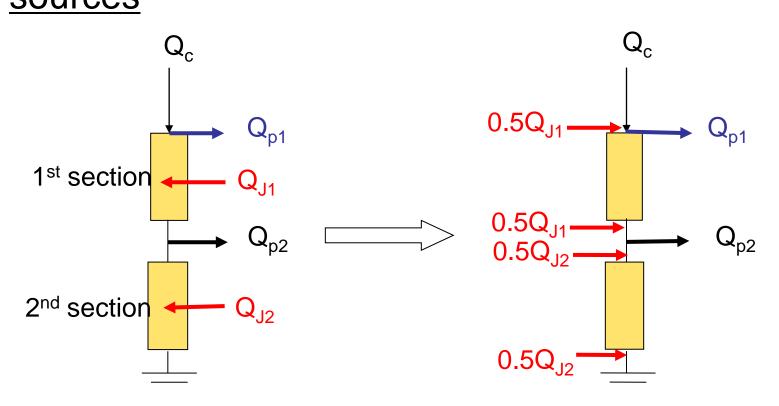


- Maximum cooling is <u>only a function of ZT</u>
- It is geometry independent
- At maximum current, <u>half</u> of the cooling power is cancelled by the Joule heating

Can we beat the ½ ZT_c² limit by redistributing the Joule heating in the material?

heating in each section to two local heat sources

Thermal circuit analysis



In analyzing multiple-section thermoelectric

materials, we can convert distributed Joule



An intuition to improve maximum cooling in graded thermoelectric materials (Zhixi Bian)



Assumption: <u>power factor</u> and <u>thermal conductivity</u> are <u>constant</u> through the materials, <u>small ZT</u>

$$S^2\sigma = \text{constant}$$

L	L/4 L/9
S	2S 3S
σ	σ/4 σ/9
R	R R

$$\Delta T_{\max} = \frac{1}{2} Z T_{C}^{2} \sum_{n=1}^{2} \frac{1}{n^{2}}$$

n= number of sections

Maximum cooling can be $\frac{33-78\% \text{ times}}{10}$ larger for 2-5 sections (S_{max}/S_{min}~10).

Zhixi Bian et al. Applied Physics Letters 2006

PURDUE



Zhixi Bian

Continuously graded materials Quest

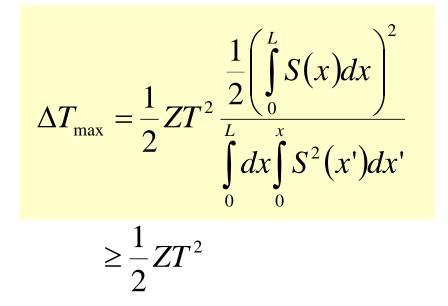
Assumption: <u>power factor</u> and <u>thermal conductivity</u> are <u>constant</u> through the materials, <u>small ZT</u>

PURDUE

NANOHUB

$$\frac{d}{dx}\left(K(x)\frac{dT(x)}{dx}\right) = -\frac{J^2}{\sigma(x)} + JT\frac{dS(x)}{dx}$$

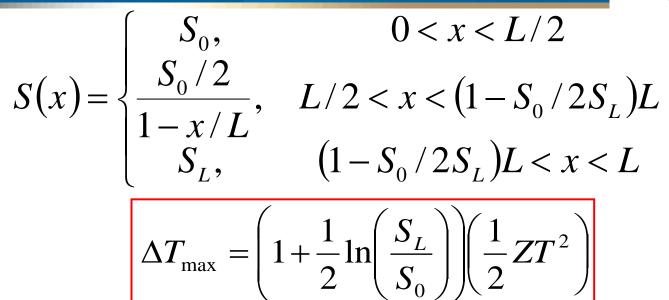
 $S(x)^2 \sigma(x) = A$



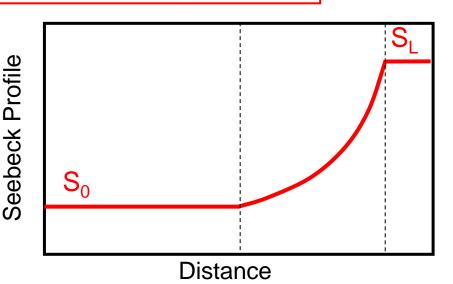
• If S increases with x monotonically, ΔT_{max} beats uniform materials Zhixi Bian, Hongyun Wang et al.; Physical Review B 2007

Analytical solution: Optimum Seebeck Profile





For the case $S^2\sigma$ =constant, ZT=small, the optimum Seebeck profile and ΔT_{max} can be calculated.



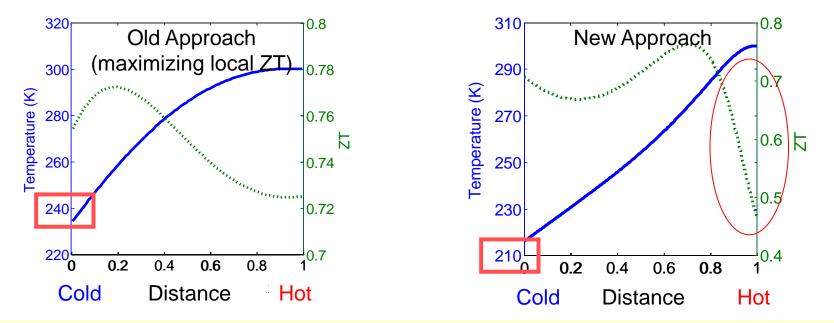
Zhixi Bian, Hongyun Wang et al.; Physical Review B 2007



Intuition: Uniform Efficiency Criterion

Maximum cooling of Bi₂Te₃ Peltier Coolers

- Conventional functionally graded TE materials try to optimize material at each location to have <u>highest ZT_{local}</u> at that location
- New analysis points to <u>uniform efficiency criterion</u>. This can increase maximum cooling of thermoelectric materials significantly.



Graded Bi₂Te₃ can increase maximum cooling of TE refrigerators from 240K to 210K (without changing max ZT)

Zhixi Bian et al. PRB 2007

Lecture 4.4 Part I Summary

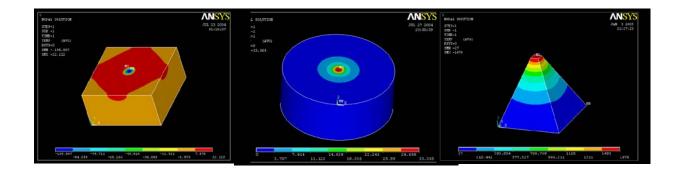


- Inhomogeneous thermoelectric materials can break the maximum cooling ½ ZT_c² (by ~30%)
- The cooling efficiency at large ∆T can also be improved.
- Analytical solution is given for constant power factor approximation.
- Uniform efficiency criterion provides physical insight into the mathematical solution
- Cooling enhancement is independent of material dimensions.

Acknowledgement: ONR-MURI Thermionic Energy Conversion Center



Can Thermoelectric Leg Geometry Improve the Performance?

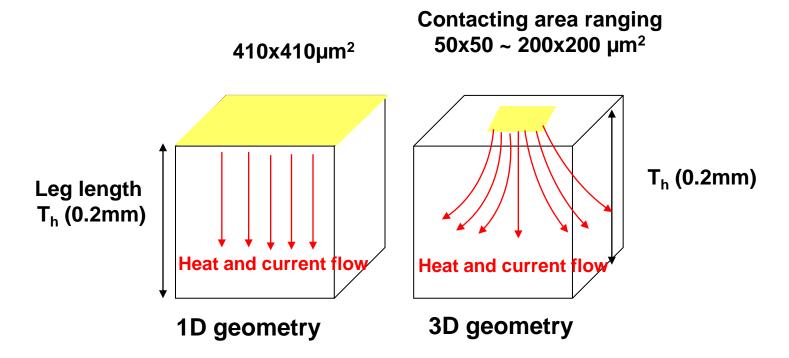


Yan Zhang, and Ali Shakouri, "Three-dimensional high cooling power density thermoelectric coolers", 23rd International conference on Thermoelectrics, Adelaide, Australia, 2004



Device Geometries



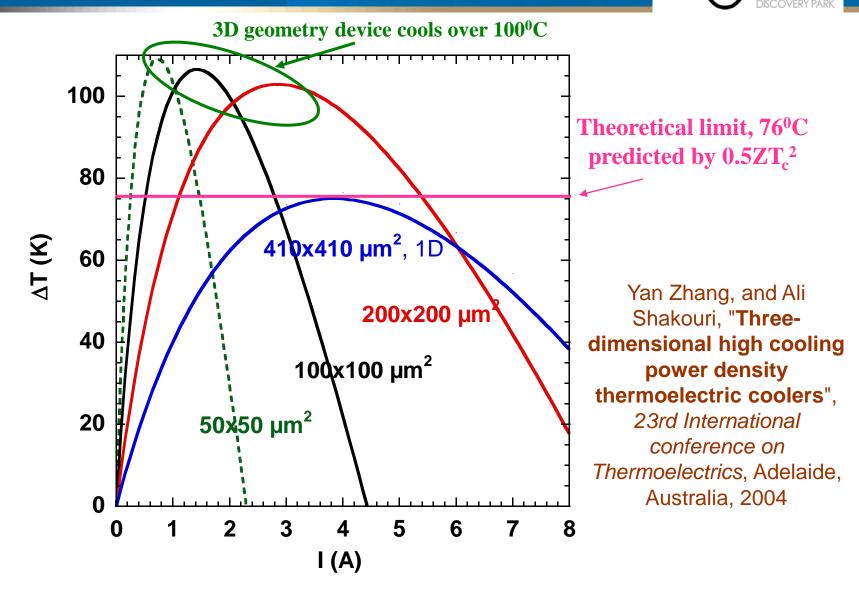


BiTe material Properties:

- α , Seebeck Coefficient, 205 μ V/K
- σ , electrical conductivity, 1010 (Ω cm)⁻¹
- κ, thermal conductivity, 1.405 K/W
- Z, figure of merit, $3.02 \cdot 10^{-3} \text{ K}^{-1}$



Cooling for various device sizes Quest

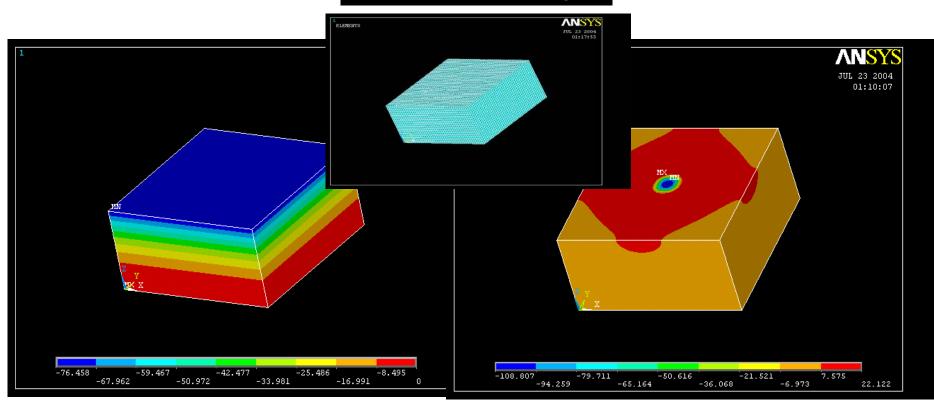




Device cooling distribution



Solid brick meshing



1D device, contact area 410x410μm² Max. Cooling, 76.5⁰C with supplied current 4A 3D device, contact area 50x50µm² Max. Cooling, 108.8⁰C with supplied current 0.8A

Seemed too good to be true???



Different opinion

 S_1

 $T_1 \\ U_1$

 S_0

T₀

U₀

 V.A Semenyuk, "Efficiency of Cooling Thermoelectric Elements of Arbitrary Shape", Journal of Engineering Physics, Vol.32 (2) p.196, 1978

Poisson Equation

$$abla^2 \varphi = -i^2 / \lambda \sigma$$

Two assumptions:

- 1. No current, heat flux due to T_1 - T_0
- 2. With current but uniform contact T_0

Conclusion: The maximum energy efficiency in the most general case is <u>independent of the shape</u> <u>of the conductor</u>

Assumption: Uniform temperature at contact area



Different Boundary Conditions at contact region:

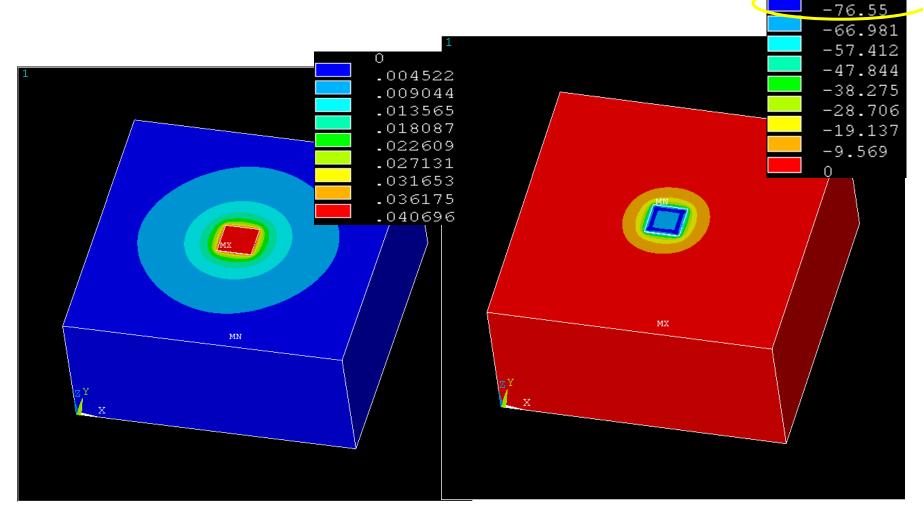
- 1. Uniform Potential;
- 2. Uniform Current Density;

Yan Zhang, Zhixi Bian and Ali Shakouri, "Improved energy conversion efficiency by optimizing the geometry of thermoelectric leg elements", *Proceedings of the 24 th International conference on Thermoelectrics*, pp.233-236, June, 2005, Clemson, SC

Yan Zhang , Gehong Zeng, Avram Bar-Cohen and Ali Shakouri, "**Is ZT the main main performance factor for hot spot cooling using 3D microrefrigerators?",** *IMAPS on Thermal Management*, 2005, Palo Alto, CA (Student Competition Award)



Boundary Condition 1: Uniform Potential



Potential Distribution

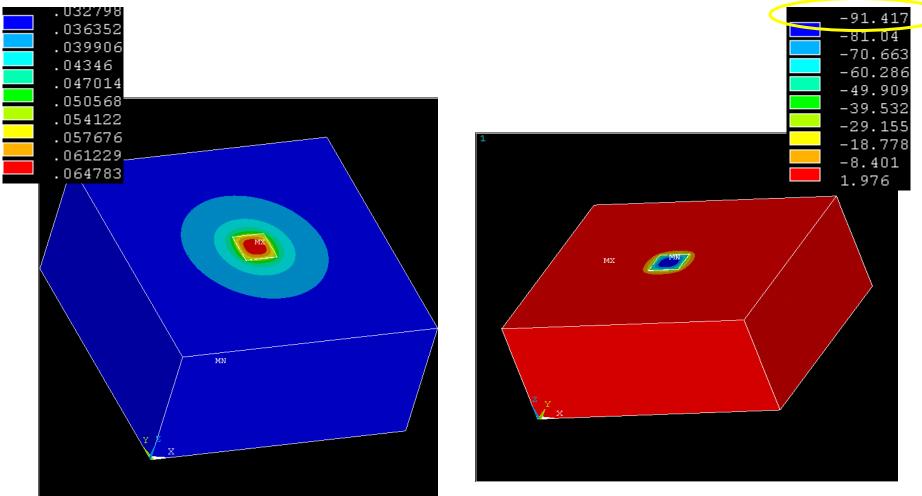
Temperature Distribution

Supplied I=0.6A



Boundary Condition 2: Uniform Current





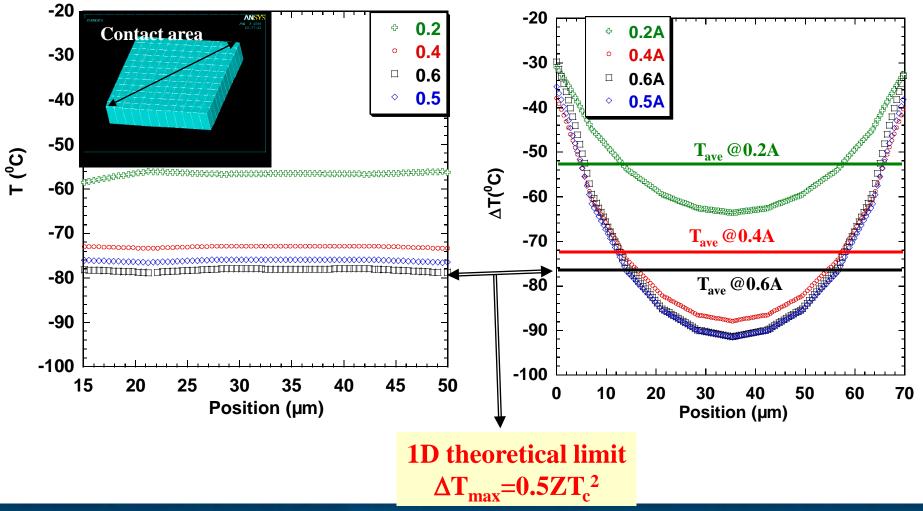
Potential Distribution

Supplied I=0.6A

A. Shakouri nanoHUB-U-Fall 2013

Current Distribution

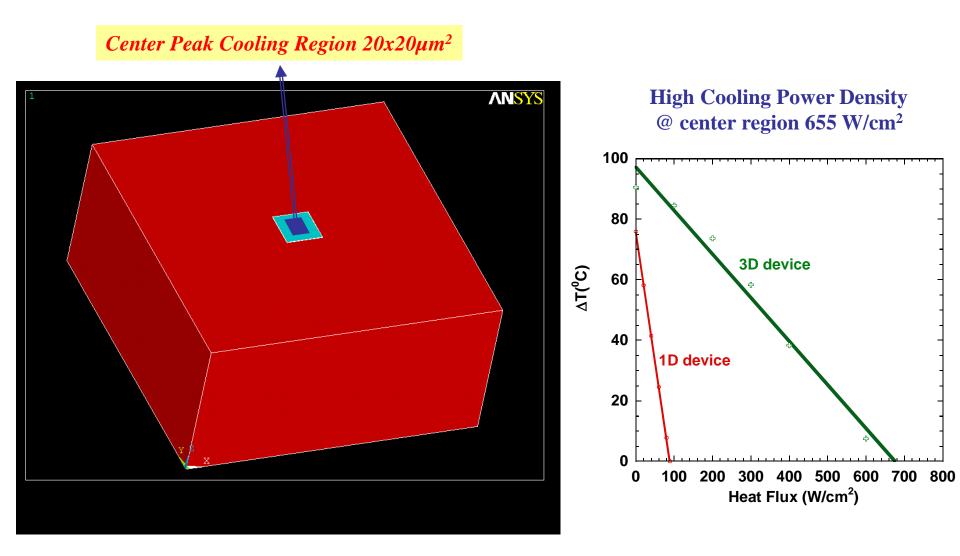
Temperature Cross-section under different Boundary Conditions





Benefit of 3D device with uniform current



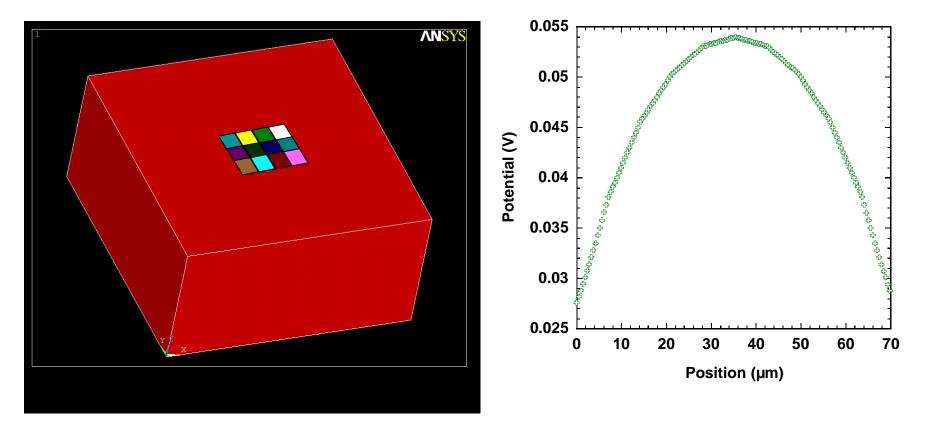




How to Achieve the uniform current injection & Quest

Array Device Solution: Send different potential to each device to achieve the uniform current profile

Diagonal Potential Distribution @ supplied 0.5A





Lecture 4.4 Part II Summary



- The 3D device can cool better than 1D under the condition of uniform current distribution;
 - The temperature distribution is non-uniform at contact area;
 - The center peak region, 20x20µm², could cool over 85°C, or cooling power density of 650 W/cm²;
- It is possible to create an array structure and manipulating the potential of each device to achieve the maximum cooling in the center;

Yan Zhang, Zhixi Bian and Ali Shakouri, "Improved energy conversion efficiency by optimizing the geometry of thermoelectric leg elements", *Proceedings of the 24 th International conference on Thermoelectrics*, pp.233-236, June, 2005, Clemson , SC

